



UF2A THRU UF2M

FEATURES:

- Plastic package has Underwriters Laboratory Flammability Classification 94V-0
- For surface mounted applications
- Glass passivated chip junctions
- Low profile package
- Easy pick and place
- Ultrafast recovery times for high efficiency
- Low forward voltage, low power loss
- Built-in strain relief, ideal for automated placement
- High temperature soldering guaranteed :
250° C/10 seconds at terminals

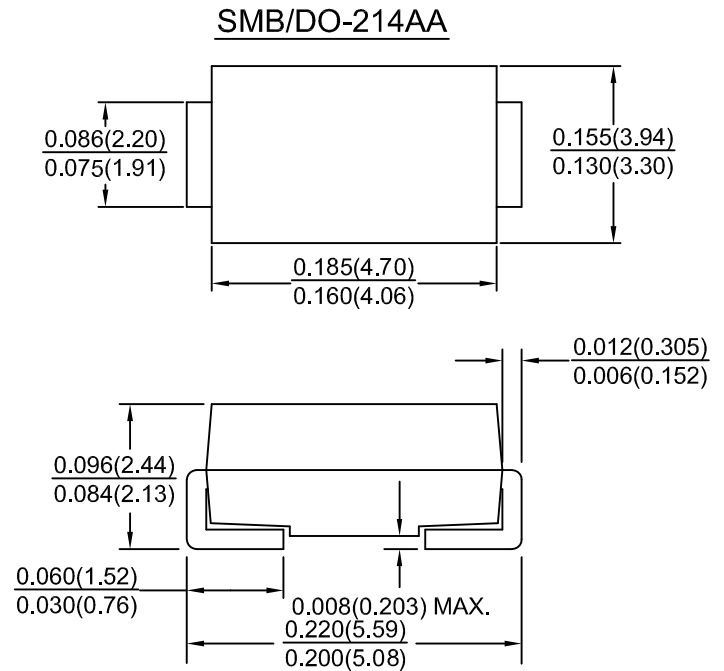
MECHANICAL DATA

Case : JEDEC DO-214AA molded plastic body over passivated chip

Terminals : Solder plated, solderable per MIL-STD-750, Method 2026

Polarity : Color band denotes cathode end

Weight : 0.002 ounce, 0.064 gram



Dimensions in inches and (millimeters)

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Rating at 25 °C ambient temperature unless otherwise specified.

Characteristic	Symbol	UF2A	UF2B	UF2D	UF2G	UF2J	UF2K	UF2M	Units
Maximum recurrent peak reverse voltage	V _{RRM}	50	100	200	400	600	800	1000	Volts
Maximum RMS voltage	V _{RMS}	35	70	140	280	420	560	700	Volts
Maximum DC blocking voltage	V _{DC}	50	100	200	400	600	800	1000	Volts
Maximum average forward rectified current at T _L =55°C	I _(AV)	2.0							Amp
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load(JEDEC Method)	I _{FSM}	50.0							Amps
Maximum instantaneous forward voltage at 2.0 A	V _F	1.0		1.4		1.7		Volts	
Maximum DC reverse current at rated DC blocking voltage	I _R	Ta=25 °C		5.0		Ta=100°C		50.0	μ A
Maximum reverse recovery time (NOTE 1)	t _{rr}	50.0				75.0			nS
Typical junction capacitance (NOTE 2)	C _J	17.0				15.0			pF
Maximum thermal resistance (NOTE 3)	R _{th-JA} R _{th-JL}	75.0				27.0			°C/W
Operating and storage temperature range	T _J , T _{stg}	-65 to +150							°C

NOTES:

- (1) Reverse recovery test condition : I_F=0.5A, I_R=1.0A, I_{rr}=0.25A
- (2) Measured at 1.0 MHz and applied reverse voltage of 4.0 Volts
- (3) P.C.B. mounted on 0.2x0.2"(5.0x5.0mm) copper pad area

RATINGS AND CHARACTERISTIC CURVES UF2A THRU UF2M

